

To our customers,

Old Company Name in Catalogs and Other Documents

On April 1st, 2010, NEC Electronics Corporation merged with Renesas Technology Corporation, and Renesas Electronics Corporation took over all the business of both companies. Therefore, although the old company name remains in this document, it is a valid Renesas Electronics document. We appreciate your understanding.

Renesas Electronics website: <http://www.renesas.com>

April 1st, 2010
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (<http://www.renesas.com>)

Send any inquiries to <http://www.renesas.com/inquiry>.

Notice

1. All information included in this document is current as of the date this document is issued. Such information, however, is subject to change without any prior notice. Before purchasing or using any Renesas Electronics products listed herein, please confirm the latest product information with a Renesas Electronics sales office. Also, please pay regular and careful attention to additional and different information to be disclosed by Renesas Electronics such as that disclosed through our website.
2. Renesas Electronics does not assume any liability for infringement of patents, copyrights, or other intellectual property rights of third parties by or arising from the use of Renesas Electronics products or technical information described in this document. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
3. You should not alter, modify, copy, or otherwise misappropriate any Renesas Electronics product, whether in whole or in part.
4. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation of these circuits, software, and information in the design of your equipment. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from the use of these circuits, software, or information.
5. When exporting the products or technology described in this document, you should comply with the applicable export control laws and regulations and follow the procedures required by such laws and regulations. You should not use Renesas Electronics products or the technology described in this document for any purpose relating to military applications or use by the military, including but not limited to the development of weapons of mass destruction. Renesas Electronics products and technology may not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations.
6. Renesas Electronics has used reasonable care in preparing the information included in this document, but Renesas Electronics does not warrant that such information is error free. Renesas Electronics assumes no liability whatsoever for any damages incurred by you resulting from errors in or omissions from the information included herein.
7. Renesas Electronics products are classified according to the following three quality grades: “Standard”, “High Quality”, and “Specific”. The recommended applications for each Renesas Electronics product depends on the product’s quality grade, as indicated below. You must check the quality grade of each Renesas Electronics product before using it in a particular application. You may not use any Renesas Electronics product for any application categorized as “Specific” without the prior written consent of Renesas Electronics. Further, you may not use any Renesas Electronics product for any application for which it is not intended without the prior written consent of Renesas Electronics. Renesas Electronics shall not be in any way liable for any damages or losses incurred by you or third parties arising from the use of any Renesas Electronics product for an application categorized as “Specific” or for which the product is not intended where you have failed to obtain the prior written consent of Renesas Electronics. The quality grade of each Renesas Electronics product is “Standard” unless otherwise expressly specified in a Renesas Electronics data sheets or data books, etc.
 - “Standard”: Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; and industrial robots.
 - “High Quality”: Transportation equipment (automobiles, trains, ships, etc.); traffic control systems; anti-disaster systems; anti-crime systems; safety equipment; and medical equipment not specifically designed for life support.
 - “Specific”: Aircraft; aerospace equipment; submersible repeaters; nuclear reactor control systems; medical equipment or systems for life support (e.g. artificial life support devices or systems), surgical implantations, or healthcare intervention (e.g. excision, etc.), and any other applications or purposes that pose a direct threat to human life.
8. You should use the Renesas Electronics products described in this document within the range specified by Renesas Electronics, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas Electronics shall have no liability for malfunctions or damages arising out of the use of Renesas Electronics products beyond such specified ranges.
9. Although Renesas Electronics endeavors to improve the quality and reliability of its products, semiconductor products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Further, Renesas Electronics products are not subject to radiation resistance design. Please be sure to implement safety measures to guard them against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas Electronics product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or system manufactured by you.
10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. Please use Renesas Electronics products in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. Renesas Electronics assumes no liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
11. This document may not be reproduced or duplicated, in any form, in whole or in part, without prior written consent of Renesas Electronics.
12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products, or if you have any other inquiries.

(Note 1) “Renesas Electronics” as used in this document means Renesas Electronics Corporation and also includes its majority-owned subsidiaries.

(Note 2) “Renesas Electronics product(s)” means any product developed or manufactured by or for Renesas Electronics.

Phase-out/Discontinued

**384-OUTPUT TFT-LCD SOURCE DRIVER
(COMPATIBLE WITH 64-GRAY SCALES)**

DESCRIPTION

The μ PD16716 is a source driver for TFT-LCDs capable of dealing with displays with 64-gray scales. Data input is based on digital input configured as 6 bits by 6 dots (2 pixels), which can realize a full-color display of 260,000 colors by output of 64 values γ -corrected by an internal D/A converter and 5-by-2 external power modules. Because the output dynamic range is as large as $V_{SS2} + 0.1$ V to $V_{DD2} - 0.1$ V, level inversion operation of the LCD's common electrode is rendered unnecessary. Also, to be able to deal with dot-line inversion, n-line inversion and column line inversion when mounted on a single side, this source driver is equipped with a built-in 6-bit D/A converter circuit whose odd output pins and even output pins respectively output gray scale voltages of differing polarity. Assuring a maximum clock frequency of 70 MHz when driving at 3.0 V, 45 MHz when driving at 2.5 V, this driver is applicable to XGA/SXGA-standard TFT-LCD panels.

FEATURES

- CMOS level input (2.5 to 3.6 V)
- 384 Outputs
- Input of 6 bits (gray scale data) by 6 dots
- Capable of outputting 64 values by means of 5-by-2 external power modules (10 units) and a D/A converter (R-DAC)
- Logic power supply voltage (V_{DD1}) : 2.5 to 3.6 V
- Driver power supply voltage (V_{DD2}) : 15.0 V \pm 0.5 V
- Output dynamic range $V_{SS2} + 0.1$ V to $V_{DD2} - 0.1$ V
- High-speed data transfer: $f_{CLK} = 70$ MHz (internal data transfer speed when operating at $V_{DD1} = 3.0$ V),
45 MHz (internal data transfer speed when operating at $V_{DD1} = 2.5$ V)
- Apply for dot-line inversion, n-line inversion and column line inversion
- Output Voltage polarity inversion function (POL)
- Display data inversion function (capable of controlling by each input port) (POL21, POL22)
- Low power control function (LPC)

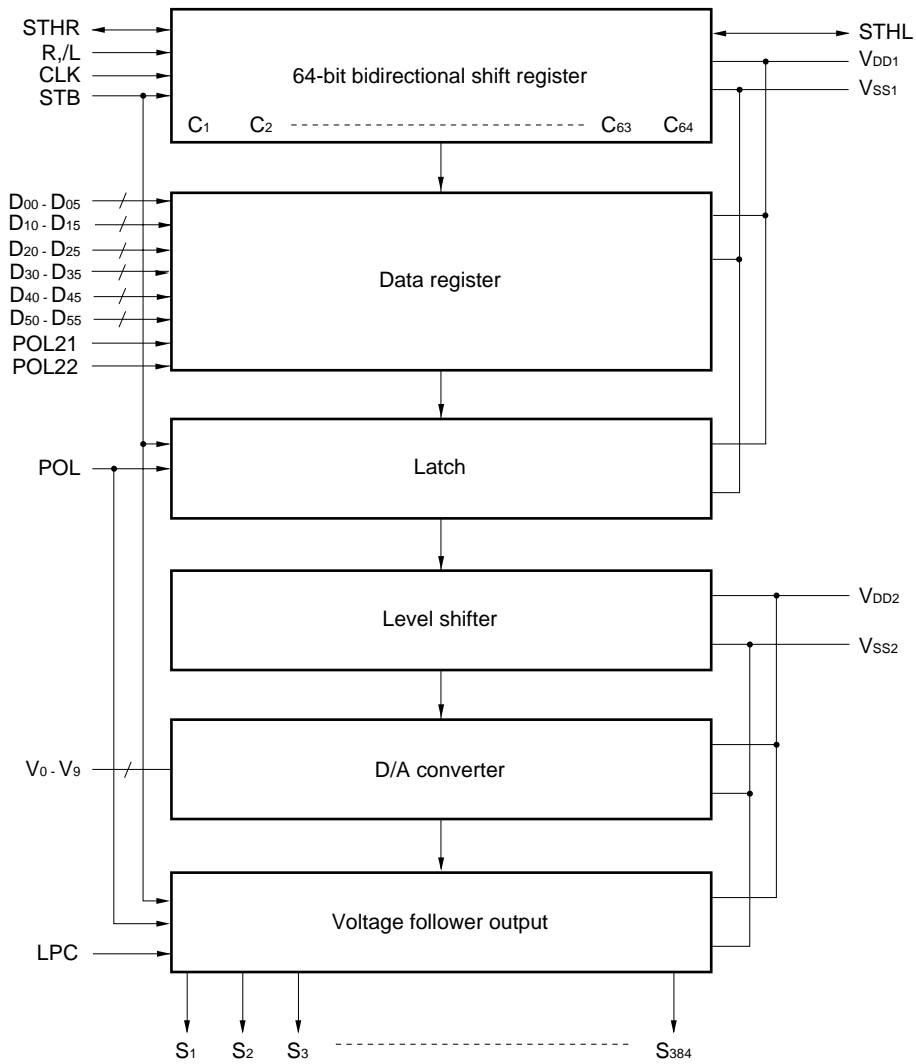
ORDERING INFORMATION

Part Number	Package
μ PD16716N-xxx	TCP (TAB package)

Remark The TCP's external shape is customized. To order your TCP's external shape, please contact one of our sales representatives.

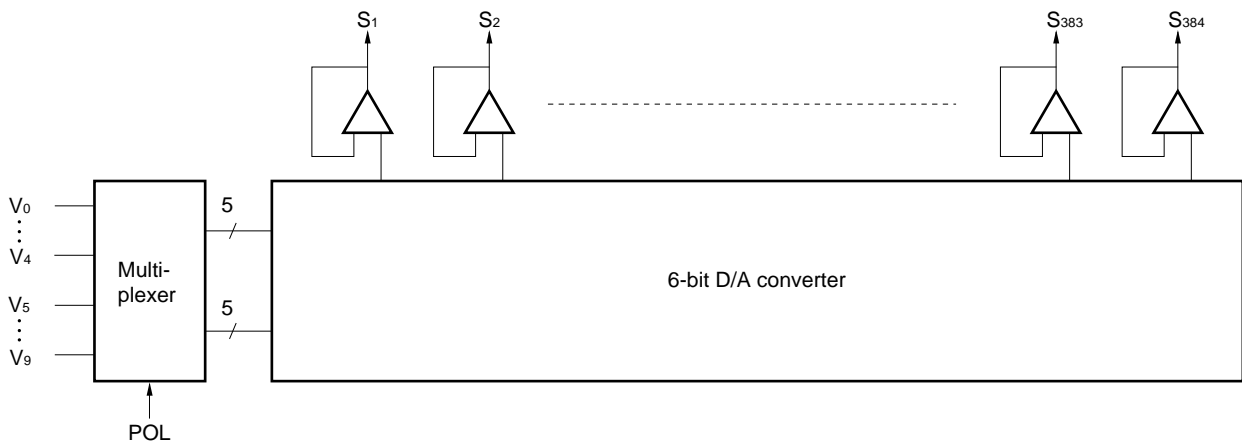
The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.
Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

1. BLOCK DIAGRAM

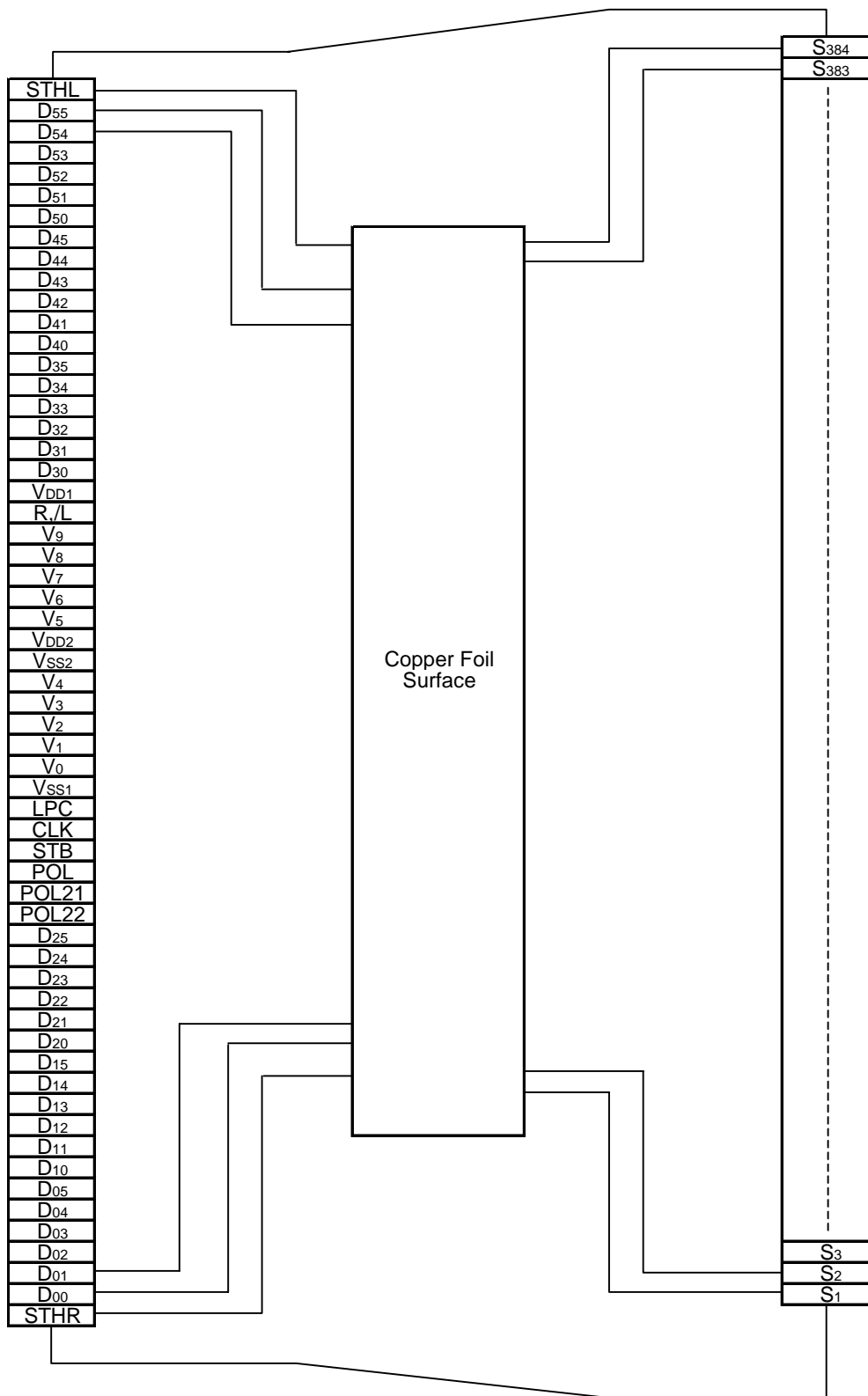


Remark /xxx indicates active low signal.

2. RELATIONSHIP BETWEEN OUTPUT CIRCUIT AND D/A CONVERTER



3. PIN CONFIGURATION (μPD16716N-xxx) (Copper Foil Surface, Face-up)



Remark This figure does not specify the TCP package.

4. PIN FUNCTIONS

(1/2)

Pin Symbol	Pin Name	I/O	Description
S ₁ to S ₃₈₄	Driver	O	The D/A converted 64-gray-scale analog voltage is output.
D ₀₀ to D ₀₅	Display data	I	The display data is input with a width of 36 bits, viz., the gray scale data (6 bits) by 6 dots (2 pixels). D _{x0} : LSB, D _{x5} : MSB
D ₁₀ to D ₁₅			
D ₂₀ to D ₂₅			
D ₃₀ to D ₃₅			
D ₄₀ to D ₄₅			
D ₅₀ to D ₅₅			
R,/L	Shift direction control	I	Refers to the shift direction control. The shift directions of the shift registers are as follows. R,/L = H : STHR input, S ₁ → S ₃₈₄ , STHL output R,/L = L : STHL input, S ₃₈₄ → S ₁ , STHR output
★ STHR	Right shift start pulse	I/O	These refer to the start pulse I/O pins when driver ICs are connected in cascade. Loading of display data starts when H is read at the rising edge of CLK. R,/L = H (right shift): STHR input, STHL output R,/L = L (left shift): STHL input, STHR output A high level should be input as the pulse of one cycle of the clock signal. If the start pulse input is more than 2CLK, the first 1CLK of the high-level input is valid.
★ STHL	Left shift start pulse	I/O	
★ CLK	Shift clock	I	Refers to the shift register's shift clock input. The display data is loaded into the data register at the rising edge. At the rising edge of the 64th clock after the start pulse input, the start pulse output reaches the high level, thus becoming the start pulse of the next-level driver. If 66-clock pulses are input after input of the start pulse, input of display data is halted automatically. The contents of the shift register are cleared at the STB's rising edge.
STB	Latch	I	The contents of the data register are transferred to the latch circuit at the rising edge. And, at the falling edge, the gray scale voltage is supplied to the driver. It is necessary to ensure input of one pulse per horizontal period.
POL	Polarity	I	POL = L : The S _{2n-1} output uses V ₀ to V ₄ as the reference supply. The S _{2n} output uses V ₅ to V ₉ as the reference supply. POL = H : The S _{2n-1} output uses V ₅ to V ₉ as the reference supply. The S _{2n} output uses V ₀ to V ₄ as the reference supply. S _{2n-1} indicates the odd output: and S _{2n} indicates the even output. Input of the POL signal is allowed the setup time (t _{POL-STB}) with respect to STB's rising edge.
★ POL21, POL22	Data inversion	I	Data inversion can invert when display data is loaded. POL21: Invert/not invert of display data D ₀₀ to D ₀₅ , D ₁₀ to D ₁₅ , D ₂₀ to D ₂₅ . POL22: Invert/not invert of display data D ₃₀ to D ₃₅ , D ₄₀ to D ₄₅ , D ₅₀ to D ₅₅ . POL21, POL22 = H : Display data is inverted. POL21, POL22 = L : Display data is not inverted.
LPC	Low power control	I	The current consumption is lowered by controlling the constant current source of the output amplifier. This pin is pulled up to the V _{DD1} power supply inside the IC. In low power mode (LPC = L), the static current consumption of V _{DD2} reduced to about 2/3 of the normal current consumption. LPC = H or Open : Normal power mode LPC = L : Low power mode

(2/2)

Pin Symbol	Pin Name	I/O	Description
V ₀ to V ₉	γ -corrected power supplies	–	Input the γ -corrected power supplies from outside by using operational amplifier. Make sure to maintain the following relationships. During the gray scale voltage output, be sure to keep the gray scale level power supply at a constant level. $V_{DD2} - 0.1\text{ V} \geq V_0 > V_1 > V_2 > V_3 > V_4 \geq 0.5\text{ V}$ $V_{DD2} \geq V_5 > V_6 > V_7 > V_8 > V_9 \geq V_{SS2} + 0.1\text{ V}$
V _{DD1}	Logic power supply	–	2.5 V to 3.6 V
V _{DD2}	Driver power supply	–	15.0 V \pm 0.5 V
V _{SS1}	Logic ground	–	Grounding
V _{SS2}	Driver ground	–	Grounding

Cautions 1. The power start sequence must be V_{DD1}, logic input, and V_{DD2} & V₀ to V₉ in that order.

Reverse this sequence to shut down. (Simultaneous power application to V_{DD2} and V₀ to V₉ is possible.)

2. To stabilize the supply voltage, please be sure to insert a 0.1 μ F bypass capacitor between V_{DD1}-V_{SS1} and V_{DD2}-V_{SS2}. Furthermore, for increased precision of the D/A converter, insertion of a bypass capacitor of about 0.01 μ F is also advised between the γ -corrected power supply terminals (V₀, V₁, V₂, ..., V₉) and V_{SS2}.

5. RELATIONSHIP BETWEEN INPUT DATA AND OUTPUT VOLTAGE VALUE

This product incorporates a 6-bit D/A converter whose odd output pins and even output pins output respectively gray scale voltages of differing polarity with respect to the LCD's counter electrode (common electrode) voltage. The D/A converter consists of ladder resistors and switches.

The ladder resistors (r0 to r62) are designed so that the ratio of LCD panel γ -compensated voltages to V_0' to V_{63}' and V_0'' to V_{63}'' is almost equivalent. For the 2 sets of five γ -compensated power supplies, V_0 to V_4 and V_5 to V_9 , respectively, input gray scale voltages of the same polarity with respect to the common voltage. When fine-gray scale voltage precision is not necessary, there is no need to connect a voltage follower circuit to the γ -compensated power supplies V_1 to V_3 and V_6 to V_8 .

Figure 5-1 shows the relationship between the driving voltages such as liquid-crystal driving voltages V_{DD2} and V_{SS2} , common electrode potential V_{COM} , and γ -corrected voltages V_0 to V_9 and the input data. Be sure to maintain the voltage relationships as follows:

$$V_{DD2} - 0.1 \text{ V} \geq V_0 > V_1 > V_2 > V_3 > V_4 \geq 0.5 V_{DD2} \geq V_5 > V_6 > V_7 > V_8 > V_9 \geq V_{SS2} + 0.1 \text{ V}.$$

Figures 5-2 and 5-3 show the relationship between input data and output voltage. This driver IC is designed for only single-sided mounting

Figure 5-1. Relationship between Input Data and γ -corrected Power Supply

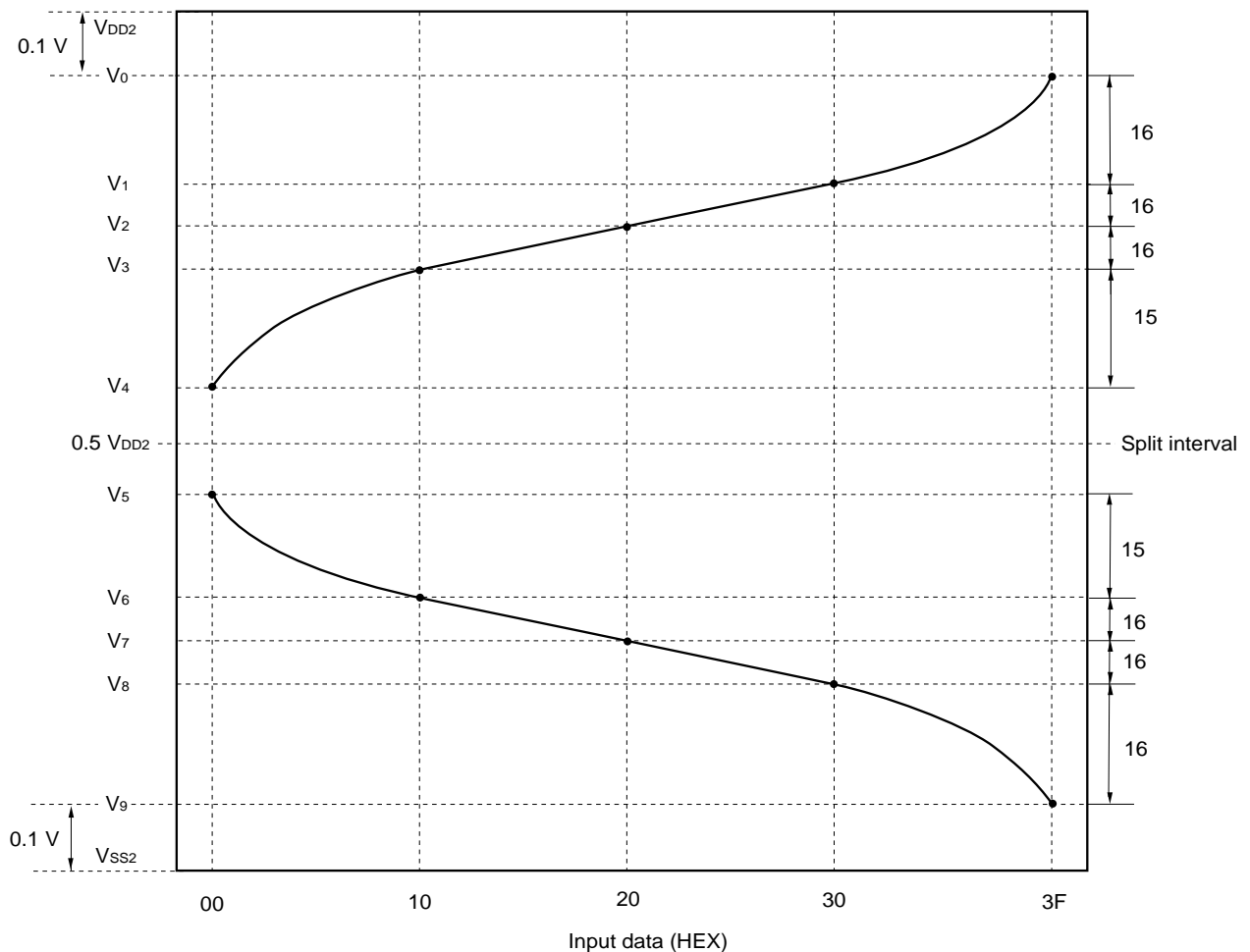
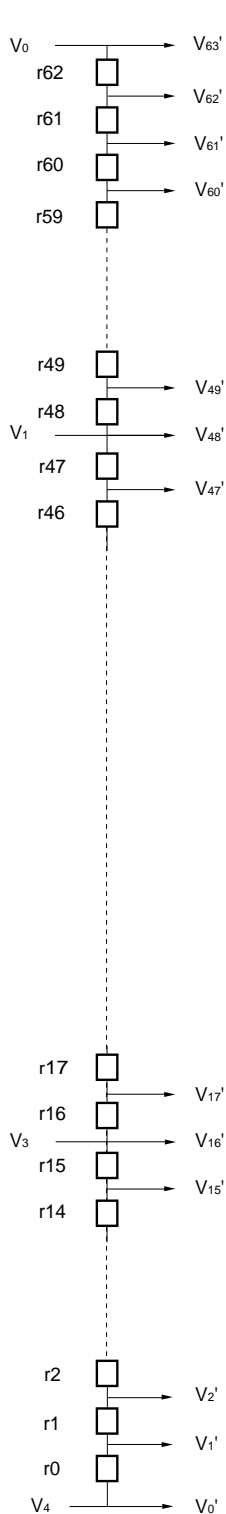


Figure 5-2. Relationship between Input Data and Output voltage
 $V_{DD2} - 0.1 V \geq V_0 > V_1 > V_2 > V_3 > V_4 \geq 0.5 V_{DD2}$, POL21, POL22 = L

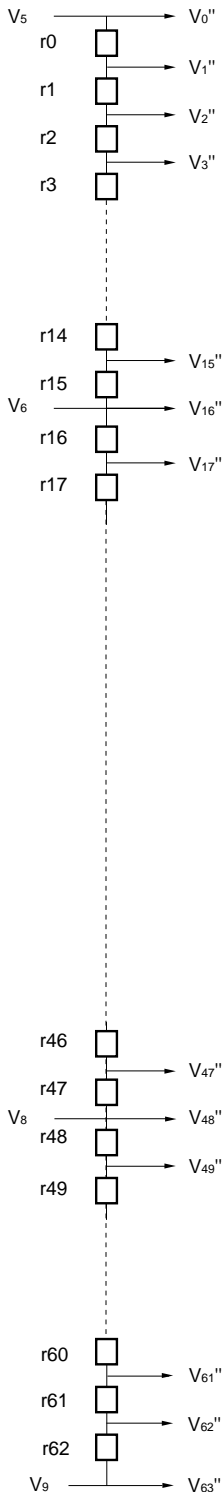


Data	D _{x7}	D _{x6}	D _{x5}	D _{x4}	D _{x3}	D _{x2}	D _{x1}	D _{x0}	Output Voltage	
00H	0	0	0	0	0	0	0	0	V _{0'}	V ₄
01H	0	0	0	0	0	0	0	1	V _{1'}	V ₄ +(V ₃ -V ₄) X
02H	0	0	0	0	0	0	1	0	V _{2'}	V ₄ +(V ₃ -V ₄) X
03H	0	0	0	0	0	0	1	1	V _{3'}	V ₄ +(V ₃ -V ₄) X
04H	0	0	0	0	0	1	0	0	V _{4'}	V ₄ +(V ₃ -V ₄) X
05H	0	0	0	0	0	1	0	1	V _{5'}	V ₄ +(V ₃ -V ₄) X
06H	0	0	0	0	0	1	1	0	V _{6'}	V ₄ +(V ₃ -V ₄) X
07H	0	0	0	0	0	1	1	1	V _{7'}	V ₄ +(V ₃ -V ₄) X
08H	0	0	0	0	1	0	0	0	V _{8'}	V ₄ +(V ₃ -V ₄) X
09H	0	0	0	0	1	0	0	1	V _{9'}	V ₄ +(V ₃ -V ₄) X
0AH	0	0	0	0	1	0	1	0	V _{10'}	V ₄ +(V ₃ -V ₄) X
0BH	0	0	0	0	1	0	1	1	V _{11'}	V ₄ +(V ₃ -V ₄) X
0CH	0	0	0	0	1	1	0	0	V _{12'}	V ₄ +(V ₃ -V ₄) X
0DH	0	0	0	0	1	1	0	1	V _{13'}	V ₄ +(V ₃ -V ₄) X
0EH	0	0	0	0	1	1	1	0	V _{14'}	V ₄ +(V ₃ -V ₄) X
0FH	0	0	0	0	1	1	1	1	V _{15'}	V ₄ +(V ₃ -V ₄) X
10H	0	0	0	1	0	0	0	0	V _{16'}	V ₃
11H	0	0	0	1	0	0	0	1	V _{17'}	V ₃ +(V ₂ -V ₃) X
12H	0	0	0	1	0	0	1	0	V _{18'}	V ₃ +(V ₂ -V ₃) X
13H	0	0	0	1	0	0	1	1	V _{19'}	V ₃ +(V ₂ -V ₃) X
14H	0	0	0	1	0	1	0	0	V _{20'}	V ₃ +(V ₂ -V ₃) X
15H	0	0	0	1	0	1	0	1	V _{21'}	V ₃ +(V ₂ -V ₃) X
16H	0	0	0	1	0	1	1	0	V _{22'}	V ₃ +(V ₂ -V ₃) X
17H	0	0	0	1	0	1	1	1	V _{23'}	V ₃ +(V ₂ -V ₃) X
18H	0	0	0	1	1	0	0	0	V _{24'}	V ₃ +(V ₂ -V ₃) X
19H	0	0	0	1	1	0	0	1	V _{25'}	V ₃ +(V ₂ -V ₃) X
1AH	0	0	0	1	1	0	1	0	V _{26'}	V ₃ +(V ₂ -V ₃) X
1BH	0	0	0	1	1	0	1	1	V _{27'}	V ₃ +(V ₂ -V ₃) X
1CH	0	0	0	1	1	1	0	0	V _{28'}	V ₃ +(V ₂ -V ₃) X
1DH	0	0	0	1	1	1	0	1	V _{29'}	V ₃ +(V ₂ -V ₃) X
1EH	0	0	0	1	1	1	1	0	V _{30'}	V ₃ +(V ₂ -V ₃) X
1FH	0	0	0	1	1	1	1	1	V _{31'}	V ₃ +(V ₂ -V ₃) X
20H	0	0	1	0	0	0	0	0	V _{32'}	V ₂
21H	0	0	1	0	0	0	0	1	V _{33'}	V ₂ +(V ₁ -V ₂) X
22H	0	0	1	0	0	0	1	0	V _{34'}	V ₂ +(V ₁ -V ₂) X
23H	0	0	1	0	0	0	1	1	V _{35'}	V ₂ +(V ₁ -V ₂) X
24H	0	0	1	0	0	1	0	0	V _{36'}	V ₂ +(V ₁ -V ₂) X
25H	0	0	1	0	0	1	0	1	V _{37'}	V ₂ +(V ₁ -V ₂) X
26H	0	0	1	0	0	1	1	0	V _{38'}	V ₂ +(V ₁ -V ₂) X
27H	0	0	1	0	0	1	1	1	V _{39'}	V ₂ +(V ₁ -V ₂) X
28H	0	0	1	0	1	0	0	0	V _{40'}	V ₂ +(V ₁ -V ₂) X
29H	0	0	1	0	1	0	0	1	V _{41'}	V ₂ +(V ₁ -V ₂) X
2AH	0	0	1	0	1	0	1	0	V _{42'}	V ₂ +(V ₁ -V ₂) X
2BH	0	0	1	0	1	0	1	1	V _{43'}	V ₂ +(V ₁ -V ₂) X
2CH	0	0	1	0	1	1	0	0	V _{44'}	V ₂ +(V ₁ -V ₂) X
2DH	0	0	1	0	1	1	0	1	V _{45'}	V ₂ +(V ₁ -V ₂) X
2EH	0	0	1	0	1	1	1	0	V _{46'}	V ₂ +(V ₁ -V ₂) X
2FH	0	0	1	0	1	1	1	1	V _{47'}	V ₂ +(V ₁ -V ₂) X
30H	0	0	1	1	0	0	0	0	V _{48'}	V ₁
31H	0	0	1	1	0	0	0	1	V _{49'}	V ₁ +(V ₀ -V ₁) X
32H	0	0	1	1	0	0	1	0	V _{50'}	V ₁ +(V ₀ -V ₁) X
33H	0	0	1	1	0	0	1	1	V _{51'}	V ₁ +(V ₀ -V ₁) X
34H	0	0	1	1	0	1	0	0	V _{52'}	V ₁ +(V ₀ -V ₁) X
35H	0	0	1	1	0	1	0	1	V _{53'}	V ₁ +(V ₀ -V ₁) X
36H	0	0	1	1	0	1	1	0	V _{54'}	V ₁ +(V ₀ -V ₁) X
37H	0	0	1	1	0	1	1	1	V _{55'}	V ₁ +(V ₀ -V ₁) X
38H	0	0	1	1	1	0	0	0	V _{56'}	V ₁ +(V ₀ -V ₁) X
39H	0	0	1	1	1	0	0	1	V _{57'}	V ₁ +(V ₀ -V ₁) X
3AH	0	0	1	1	1	0	1	0	V _{58'}	V ₁ +(V ₀ -V ₁) X
3BH	0	0	1	1	1	0	1	1	V _{59'}	V ₁ +(V ₀ -V ₁) X
3CH	0	0	1	1	1	1	0	0	V _{60'}	V ₁ +(V ₀ -V ₁) X
3DH	0	0	1	1	1	1	0	1	V _{61'}	V ₁ +(V ₀ -V ₁) X
3EH	0	0	1	1	1	1	1	0	V _{62'}	V ₁ +(V ₀ -V ₁) X
3FH	0	0	1	1	1	1	1	1	V _{63'}	V ₀

m	(Ω)
r0	570
r1	620
r2	620
r3	600
r4	570
r5	340
r6	240
r7	240
r8	210
r9	210
r10	210
r11	240
r12	210
r13	210
r14	200
r15	230
r16	170
r17	170
r18	150
r19	150
r20	150
r21	150
r22	130
r23	120
r24	130
r25	130
r26	120
r27	130
r28	120
r29	120
r30	130
r31	150
r32	120
r33	120
r34	120
r35	130
r36	120
r37	120
r38	120
r39	120
r40	130
r41	120
r42	130
r43	130
r44	130
r45	150
r46	130
r47	210
r48	170
r49	170
r50	150
r51	180
r52	180
r53	180
r54	210
r55	260
r56	320
r57	310
r58	320
r59	380
r60	480
r61	570
r62	930
rtotal	14650

Caution There is no connection between V₄ and V₅ terminal in the chip.

Figure 5-3. Relationship between Input Data and Output voltage
 $0.5 V_{DD2} \geq V_4 > V_5 > V_6 > V_7 > V_8 > V_9 \geq V_{SS2} + 0.1 V$, POL21, POL22 = L



Data	Dx5	Dx4	Dx3	Dx2	Dx1	Dx0	Output Voltage	
00H	0	0	0	0	0	0	V0''	V5
01H	0	0	0	0	0	1	V1''	V6+(V5-V6) X
02H	0	0	0	0	1	0	V2''	V6+(V5-V6) X
03H	0	0	0	0	1	1	V3''	V6+(V5-V6) X
04H	0	0	0	1	0	0	V4''	V6+(V5-V6) X
05H	0	0	0	1	0	1	V5''	V6+(V5-V6) X
06H	0	0	0	1	1	0	V6''	V6+(V5-V6) X
07H	0	0	0	1	1	1	V7''	V6+(V5-V6) X
08H	0	0	1	0	0	0	V8''	V6+(V5-V6) X
09H	0	0	1	0	0	1	V9''	V6+(V5-V6) X
0AH	0	0	1	0	1	0	V10''	V6+(V5-V6) X
0BH	0	0	1	0	1	1	V11''	V6+(V5-V6) X
0CH	0	0	1	1	0	0	V12''	V6+(V5-V6) X
0DH	0	0	1	1	0	1	V13''	V6+(V5-V6) X
0EH	0	0	1	1	1	0	V14''	V6+(V5-V6) X
0FH	0	0	1	1	1	1	V15''	V6+(V5-V6) X
10H	0	1	0	0	0	0	V16''	V6
11H	0	1	0	0	0	1	V17''	V7+(V6-V7) X
12H	0	1	0	0	1	0	V18''	V7+(V6-V7) X
13H	0	1	0	0	1	1	V19''	V7+(V6-V7) X
14H	0	1	0	1	0	0	V20''	V7+(V6-V7) X
15H	0	1	0	1	0	1	V21''	V7+(V6-V7) X
16H	0	1	0	1	1	0	V22''	V7+(V6-V7) X
17H	0	1	0	1	1	1	V23''	V7+(V6-V7) X
18H	0	1	1	0	0	0	V24''	V7+(V6-V7) X
19H	0	1	1	0	0	1	V25''	V7+(V6-V7) X
1AH	0	1	1	0	1	0	V26''	V7+(V6-V7) X
1BH	0	1	1	0	1	1	V27''	V7+(V6-V7) X
1CH	0	1	1	1	0	0	V28''	V7+(V6-V7) X
1DH	0	1	1	1	0	1	V29''	V7+(V6-V7) X
1EH	0	1	1	1	1	0	V30''	V7+(V6-V7) X
1FH	0	1	1	1	1	1	V31''	V7+(V6-V7) X
20H	1	0	0	0	0	0	V32''	V7
21H	1	0	0	0	0	1	V33''	V8+(V7-V8) X
22H	1	0	0	0	1	0	V34''	V8+(V7-V8) X
23H	1	0	0	0	1	1	V35''	V8+(V7-V8) X
24H	1	0	0	1	0	0	V36''	V8+(V7-V8) X
25H	1	0	0	1	0	1	V37''	V8+(V7-V8) X
26H	1	0	0	1	1	0	V38''	V8+(V7-V8) X
27H	1	0	0	1	1	1	V39''	V8+(V7-V8) X
28H	1	0	1	0	0	0	V40''	V8+(V7-V8) X
29H	1	0	1	0	0	1	V41''	V8+(V7-V8) X
2AH	1	0	1	0	1	0	V42''	V8+(V7-V8) X
2BH	1	0	1	0	1	1	V43''	V8+(V7-V8) X
2CH	1	0	1	1	0	0	V44''	V8+(V7-V8) X
2DH	1	0	1	1	0	1	V45''	V8+(V7-V8) X
2EH	1	0	1	1	1	0	V46''	V8+(V7-V8) X
2FH	1	0	1	1	1	1	V47''	V8+(V7-V8) X
30H	1	1	0	0	0	0	V48''	V8
31H	1	1	0	0	0	1	V49''	V9+(V8-V9) X
32H	1	1	0	0	1	0	V50''	V9+(V8-V9) X
33H	1	1	0	0	1	1	V51''	V9+(V8-V9) X
34H	1	1	0	1	0	0	V52''	V9+(V8-V9) X
35H	1	1	0	1	0	1	V53''	V9+(V8-V9) X
36H	1	1	0	1	1	0	V54''	V9+(V8-V9) X
37H	1	1	0	1	1	1	V55''	V9+(V8-V9) X
38H	1	1	1	0	0	0	V56''	V9+(V8-V9) X
39H	1	1	1	0	0	1	V57''	V9+(V8-V9) X
3AH	1	1	1	0	1	0	V58''	V9+(V8-V9) X
3BH	1	1	1	0	1	1	V59''	V9+(V8-V9) X
3CH	1	1	1	1	0	0	V60''	V9+(V8-V9) X
3DH	1	1	1	1	0	1	V61''	V9+(V8-V9) X
3EH	1	1	1	1	1	0	V62''	V9+(V8-V9) X
3FH	1	1	1	1	1	1	V63''	V9

rn	(Ω)
r0	570
r1	620
r2	620
r3	600
r4	570
r5	340
r6	240
r7	240
r8	210
r9	210
r10	210
r11	240
r12	210
r13	210
r14	200
r15	230
r16	170
r17	170
r18	150
r19	150
r20	150
r21	150
r22	130
r23	120
r24	130
r25	130
r26	120
r27	130
r28	120
r29	120
r30	130
r31	150
r32	120
r33	120
r34	120
r35	130
r36	120
r37	120
r38	120
r39	120
r40	130
r41	120
r42	130
r43	130
r44	130
r45	150
r46	130
r47	210
r48	170
r49	170
r50	150
r51	180
r52	180
r53	180
r54	210
r55	260
r56	320
r57	310
r58	320
r59	380
r60	480
r61	570
r62	930
rtotal	14650

Caution There is no connection between V4 and V5 terminal in the chip.

6. RELATIONSHIP BETWEEN INPUT DATA AND OUTPUT PIN

Data format: 6 bits × 2 RGBs (6 dots)

Input width : 36 bits (2-pixel data)

R,/L = H (Right shift)

Output	S ₁	S ₂	S ₃	S ₄	...	S ₃₈₃	S ₃₈₄
Data	D ₀₀ to D ₀₅	D ₁₀ to D ₁₅	D ₂₀ to D ₂₅	D ₃₀ to D ₃₅	...	D ₄₀ to D ₄₅	D ₅₀ to D ₅₅

R,/L = L (Left shift)

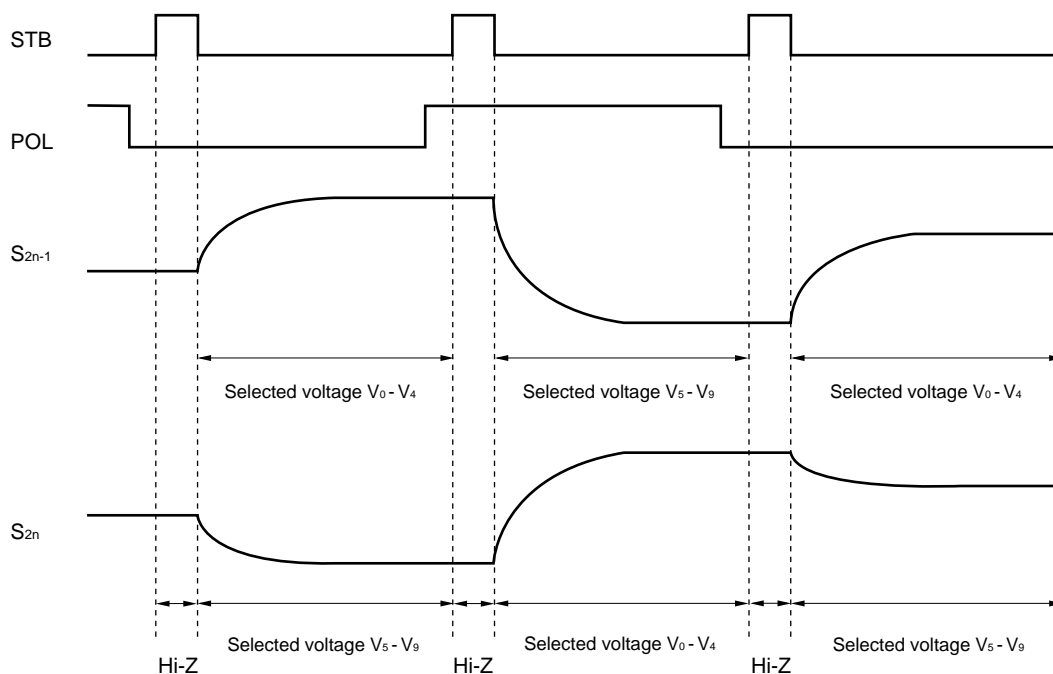
Output	S ₁	S ₂	S ₃	S ₄	...	S ₃₈₃	S ₃₈₄
Data	D ₀₀ to D ₀₅	D ₁₀ to D ₁₅	D ₂₀ to D ₂₅	D ₃₀ to D ₃₅	...	D ₄₀ to D ₄₅	D ₅₀ to D ₅₅

POL	S _{2n-1} <small>Note</small>	S _{2n} <small>Note</small>
L	V ₀ to V ₄	V ₅ to V ₉
H	V ₅ to V ₉	V ₀ to V ₄

Note S_{2n-1} (Odd output), S_{2n} (Even output)

7. RELATIONSHIP BETWEEN STB, POL, AND OUTPUT WAVEFORM

The output voltage is written to the LCD panel synchronized with the STB falling edge.



8. RELATIONSHIP BETWEEN STB, CLK, AND OUTPUT WAVEFORM

The output voltage is written to the LCD panel synchronized with the STB falling edge.

Figure 8-1. Output Circuit Block Diagram

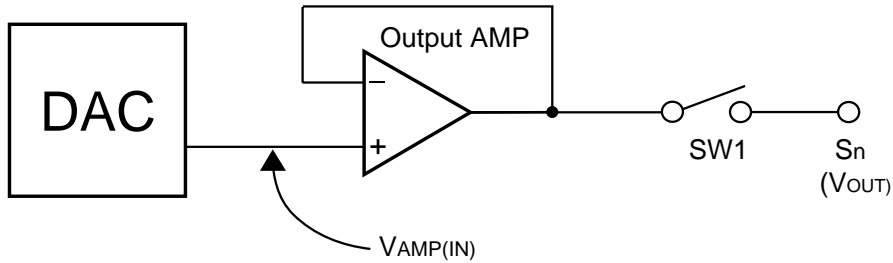
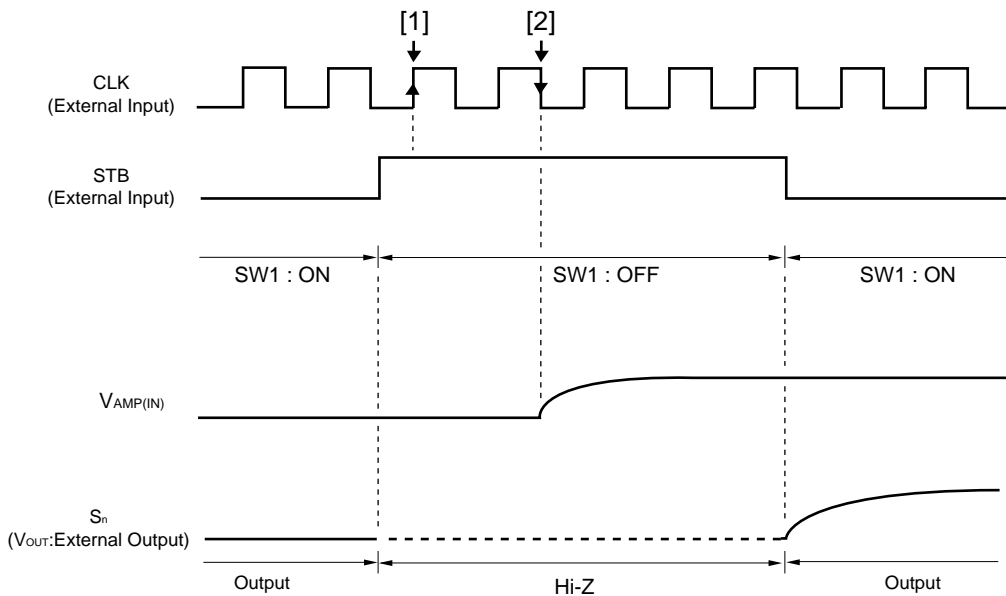


Figure 8-2. Output Circuit Timing Waveform



- Remarks 1.** STB = L : SW1 = ON
 STB = H : SW1 = OFF
- 2.** STB = "H" is acknowledged at timing [1].
- 3.** The display data latch is completed at timing [2] and the input voltage ($V_{AMP(IN)}$: gray-scale level voltage) of the output amplifier changes.

9. ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings ($T_A = +25^{\circ}\text{C}$, $V_{SS1} = V_{SS2} = 0\text{ V}$)

Parameter	Symbol	Rating	Unit
Logic Part Supply Voltage	V_{DD1}	-0.5 to +4.0	V
Driver Part Supply Voltage	V_{DD2}	-0.5 to +17.0	V
Logic Part Input Voltage	V_{I1}	-0.5 to $V_{DD1} + 0.5$	V
Driver Part Input Voltage	V_{I2}	-0.5 to $V_{DD2} + 0.5$	V
Logic Part Output Voltage	V_{O1}	-0.5 to $V_{DD1} + 0.5$	V
Driver Part Output Voltage	V_{O2}	-0.5 to $V_{DD2} + 0.5$	V
Operating Ambient Temperature	T_A	-10 to +75	$^{\circ}\text{C}$
Storage Temperature	T_{stg}	-55 to +125	$^{\circ}\text{C}$

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Recommended Operating Range ($T_A = -10$ to $+75^{\circ}\text{C}$, $V_{SS1} = V_{SS2} = 0\text{ V}$)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Logic Part Supply Voltage	V_{DD1}		2.5		3.6	V
Driver Part Supply Voltage	V_{DD2}		14.5	15.0	15.5	V
High-Level Input Voltage	V_{IH}		$0.7 V_{DD1}$		V_{DD1}	V
Low-Level Input Voltage	V_{IL}		0		$0.3 V_{DD1}$	V
γ -Corrected Voltage	V_0 to V_9		$V_{SS2} + 0.1$		$V_{DD2} - 0.1$	V
Driver Part Output Voltage	V_O		$V_{SS2} + 0.1$		$V_{DD2} - 0.1$	V
Clock Frequency	f_{CLK}	$V_{DD1} = 3.0\text{ V}$			70	MHz
		$V_{DD1} = 2.5\text{ V}$			45	MHz

★ **Electrical Characteristics** ($T_A = -10$ to $+75^\circ\text{C}$, $V_{DD1} = 2.5$ to 3.6 V, $V_{DD2} = 15.0$ V \pm 0.5 V, $V_{SS1} = V_{SS2} = 0$ V, Unless otherwise specified, power mode = normal, Bcont = open)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input Leak Current	I_{IL}				± 1.0	μA
High-Level Output Voltage	V_{OH}	STHR (STHL), $I_{OH} = 0$ mA	$V_{DD1} - 0.1$			V
Low-Level Output Voltage	V_{OL}	STHR (STHL), $I_{OL} = 0$ mA			0.1	V
γ -Corrected Supply Current	I_γ	$V_{DD2} = 15.0$ V V_0 to $V_4 = V_5$ to $V_9 = 7.5$ V V_0 pin, V_5 pin	200		800	μA
		V_4 pin, V_9 pin	-800		-200	μA
Driver Output Current	I_{VOH}	$V_X = 14.0$ V, $V_{OUT} = 13.5$ V		-75	-30	μA
	I_{VOL}	$V_X = 1.0$ V, $V_{OUT} = 1.5$ V	30	90		μA
Output Voltage Deviation	ΔV_O	$T_A = +25^\circ\text{C}$, $V_{OUT} = 3.0$ V, 7.5 V, 12.0 V		± 10	± 20	mV
Output swing difference deviation	ΔV_{P-P1}	$V_{DD1} = 3.3$ V, $T_A = +25^\circ\text{C}$	$V_{OUT} = 7.0$ to 8.0 V	± 5	± 10	mV
	ΔV_{P-P2}	$V_{DD2} = 15.0$ V, $T_A = +25^\circ\text{C}$	$V_{OUT} = 1.6$ to 12.8 V	± 7	± 13	mV
	ΔV_{P-P3}	$T_A = +25^\circ\text{C}$	$V_{OUT} = 1.0$ to 14.0 V	± 10	± 20	mV
Logic Part Dynamic Current Consumption	I_{DD1}	V_{DD1}		5	12	mA
Driver Part Dynamic Current Consumption	I_{DD2}	V_{DD2} , with no load		8	16	mA

Cautions 1. $f_{STB} = 64$ kHz, $f_{CLK} = 54$ MHz.

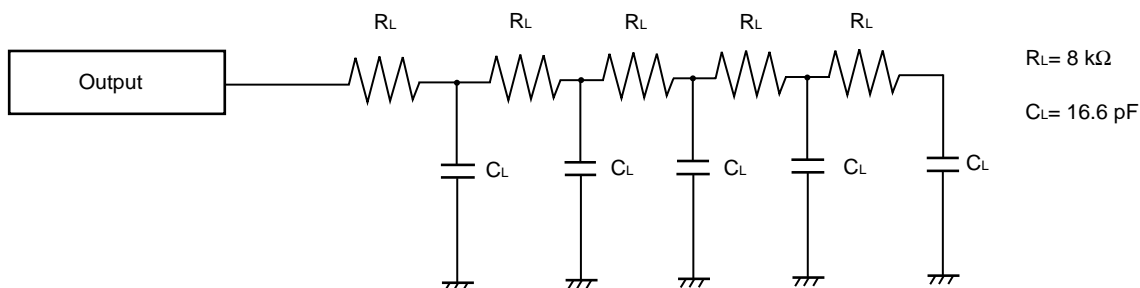
2. The TYP. values refer to an all black or all white input pattern. The MAX. value refers to the measured values in the dot checkerboard input pattern.
3. Refers to the current consumption per driver when cascades are connected under the assumption of XGA single-sided mounting (8 units).

★ **Switching Characteristics** ($T_A = -10$ to $+75^\circ\text{C}$, $V_{DD1} = 2.5$ to 3.6 V, $V_{DD2} = 15.0$ V \pm 0.5 V, $V_{SS1} = V_{SS2} = 0$ V ,
 Unless otherwise specified, power mode = normal, Bcont = open)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Start Pulse Delay Time	t_{PLH1}	$C_L = 15$ pF			12	ns
Driver Output Delay Time	t_{PLH2}	$C_L = 83$ pF, $R_L = 40$ k Ω			6	μ s
	t_{PLH3} Note				12	μ s
	t_{PHL2}				7	μ s
	t_{PHL3} Note				12	μ s
Input Capacitance	C_{i1}	STHR (STHL) excluded, $T_A = +25^\circ\text{C}$		5	10	pF
	C_{i2}	STHR (STHL), $T_A = +25^\circ\text{C}$		10	15	pF

Note t_{PLH3}/t_{PHL3} are specified as the time it takes to reach the target voltage $\pm 2\%$.

<Measurement Condition>



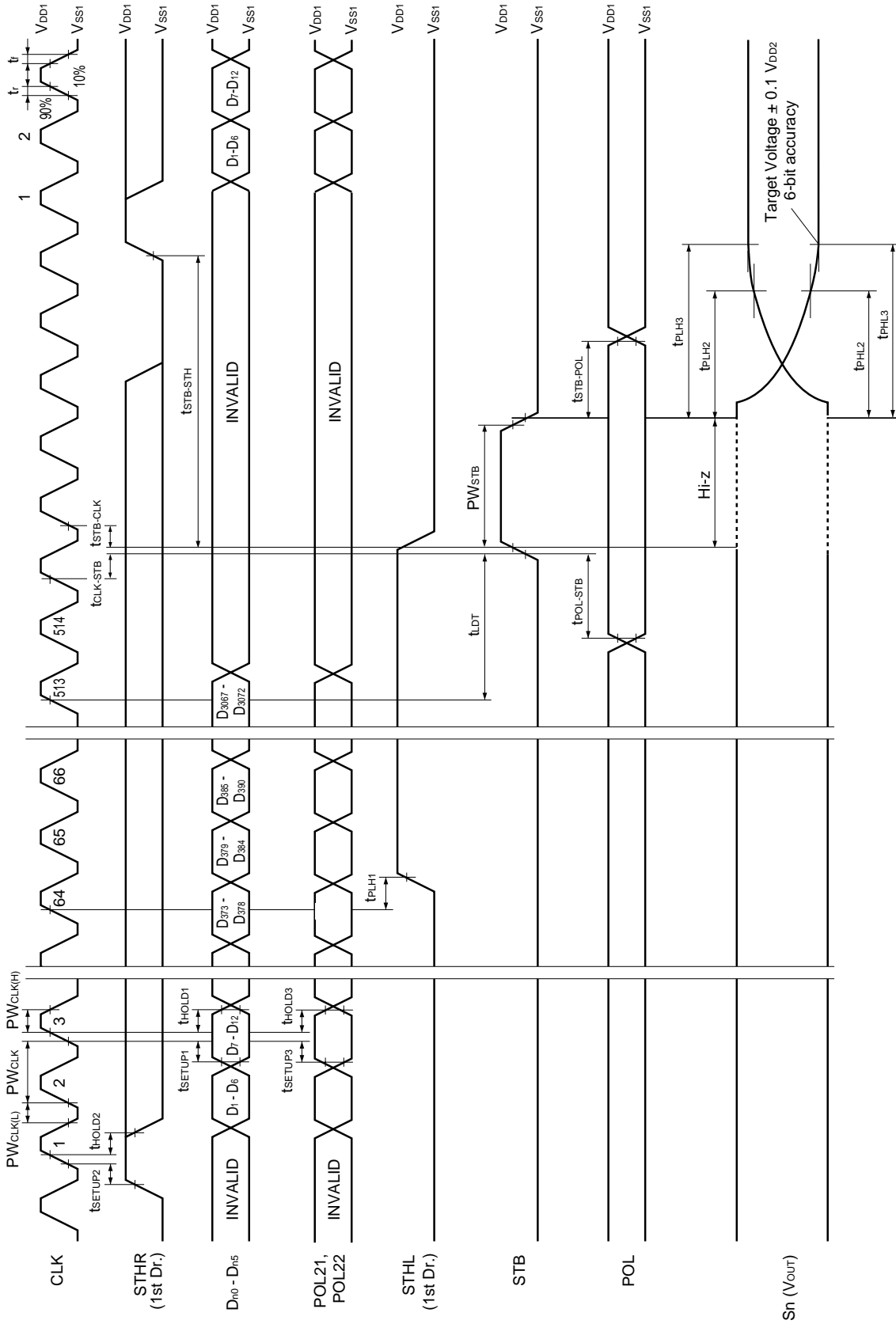
Timing Requirement ($T_A = -10$ to $+75^\circ\text{C}$, $V_{DD1} = 2.5$ to 3.6 V, $V_{SS1} = 0$ V, $t_r = t_f = 5.0$ ns)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Clock Pulse Width	PW _{CLK}	$V_{DD1} = 3.3 \text{ V} \pm 0.3 \text{ V}$	14			ns
		$V_{DD1} = 2.5$ to 3.0 V	22			ns
Clock Pulse High Period	PW _{CLK(H)}		4			ns
Clock Pulse Low Period	PW _{CLK(L)}		4			ns
Data Setup Time	t _{SETUP1}		2			ns
Data Hold Time	t _{HOLD1}		2			ns
Start Pulse Setup Time	t _{SETUP2}		2			ns
Start Pulse Hold Time	t _{HOLD2}		2			ns
POL21, POL22 Setup Time	t _{SETUP3}		2			ns
POL21, POL22 Hold Time	t _{HOLD3}		2			ns
STB Pulse Width	PW _{STB}		1.5			μs
Last Data Timing	t _{LDT}		2			CLK
CLK-STB Time	t _{CLK-STB}	CLK \uparrow \rightarrow STB \uparrow	4			ns
STB-CLK Time	t _{STB-CLK}	STB \uparrow \rightarrow CLK \uparrow	4			ns
Time between STB and Start Pulse	t _{STB-STH}	STB \uparrow \rightarrow STHR (STHL) \uparrow	2			CLK
POL-STB Time	t _{POL-STB}	POL \uparrow or \downarrow \rightarrow STB \uparrow	-5			ns
STB-POL Time	t _{STB-POL}	STB \downarrow \rightarrow POL \downarrow or \uparrow	4			ns

Remark Unless otherwise specified, the input level is defined to be $V_{IH} = 0.7 V_{DD1}$, $V_{IL} = 0.3 V_{DD1}$.

Switching Characteristics Waveform

Unless otherwise specified, the input level is defined to be $V_{IH} = 0.7 V_{DD1}$, $V_{IL} = 0.3 V_{DD1}$.



10. RECOMMENDED SOLDERING CONDITIONS

The following conditions must be met for soldering conditions of the μ PD16716.

For more details, refer to the **Semiconductor Device Mounting Technology Manual (C10535E)**.

Please consult with our sales offices in case other soldering process is used, or in case the soldering is done under different conditions.

μ PD16716N-xxx : TCP (TAB package)

Mounting Condition	Mounting Method	Condition
Thermocompression	Soldering	Heating tool 300 to 350°C: heating for 2 to 3 seconds: pressure 100g (per solder)
	ACF (Adhesive Conductive Film)	Temporary bonding 70 to 100°C: pressure 3 to 8 kg/cm ² : time 3 to 5 seconds. Real bonding 165 to 180°C: pressure 25 to 45 kg/cm ² : time 30 to 40 seconds. (When using the anisotropy conductive film SUMIZAC1003 of Sumitomo Bakelite, Ltd.)

Caution To find out the detailed conditions for packaging the ACF part, please contact the ACF manufacturing company. Be sure to avoid using two or more packaging methods at a time.

[MEMO]

[MEMO]

NOTES FOR CMOS DEVICES

① PRECAUTION AGAINST ESD FOR SEMICONDUCTORS

Note:

Strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

② HANDLING OF UNUSED INPUT PINS FOR CMOS

Note:

No connection for CMOS device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

③ STATUS BEFORE INITIALIZATION OF MOS DEVICES

Note:

Power-on does not necessarily define initial status of MOS device. Production process of MOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed immediately after power-on for devices having reset function.

Reference Documents

NEC Semiconductor Device Reliability / Quality Control System (C10983E)

Quality Grades to NEC's Semiconductor Devices (C11531E)

- **The information in this document is current as of May, 2001. The information is subject to change without notice. For actual design-in, refer to the latest publications of NEC's data sheets or data books, etc., for the most up-to-date specifications of NEC semiconductor products. Not all products and/or types are available in every country. Please check with an NEC sales representative for availability and additional information.**
 - No part of this document may be copied or reproduced in any form or by any means without prior written consent of NEC. NEC assumes no responsibility for any errors that may appear in this document.
 - NEC does not assume any liability for infringement of patents, copyrights or other intellectual property rights of third parties by or arising from the use of NEC semiconductor products listed in this document or any other liability arising from the use of such products. No license, express, implied or otherwise, is granted under any patents, copyrights or other intellectual property rights of NEC or others.
 - Descriptions of circuits, software and other related information in this document are provided for illustrative purposes in semiconductor product operation and application examples. The incorporation of these circuits, software and information in the design of customer's equipment shall be done under the full responsibility of customer. NEC assumes no responsibility for any losses incurred by customers or third parties arising from the use of these circuits, software and information.
 - While NEC endeavours to enhance the quality, reliability and safety of NEC semiconductor products, customers agree and acknowledge that the possibility of defects thereof cannot be eliminated entirely. To minimize risks of damage to property or injury (including death) to persons arising from defects in NEC semiconductor products, customers must incorporate sufficient safety measures in their design, such as redundancy, fire-containment, and anti-failure features.
 - NEC semiconductor products are classified into the following three quality grades:
 - "Standard", "Special" and "Specific". The "Specific" quality grade applies only to semiconductor products developed based on a customer-designated "quality assurance program" for a specific application. The recommended applications of a semiconductor product depend on its quality grade, as indicated below. Customers must check the quality grade of each semiconductor product before using it in a particular application.
 - "Standard": Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots
 - "Special": Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)
 - "Specific": Aircraft, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems and medical equipment for life support, etc.
- The quality grade of NEC semiconductor products is "Standard" unless otherwise expressly specified in NEC's data sheets or data books, etc. If customers wish to use NEC semiconductor products in applications not intended by NEC, they must contact an NEC sales representative in advance to determine NEC's willingness to support a given application.
- (Note)
- (1) "NEC" as used in this statement means NEC Corporation and also includes its majority-owned subsidiaries.
 - (2) "NEC semiconductor products" means any semiconductor product developed or manufactured by or for NEC (as defined above).